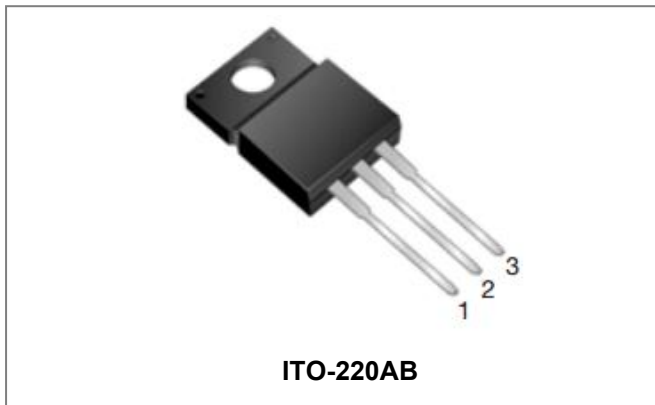


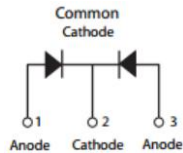
STF40H150C SCHOTTKY RECTIFIER



Features

- 175 °C T_J operation
- Ultralow forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Trench MOS Schottky technology
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	V _{RRM}	-	150	V
Working Peak Reverse Voltage	V _{RWM}			
DC Blocking Voltage	V _R			
Average Rectified Forward Current	I _{F(AV)}	50% duty cycle @T _c =85°C, rectangular wave form	20(Per Leg) 40(Per Device)	A
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	I _{FSM}	8.3ms, Half Sine pulse	200	A

Electrical Characteristics:

Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop (Per Leg)*	V _{F1}	@5A, Pulse, T _J = 25 °C	0.68	-	V
		@10A, Pulse, T _J = 25 °C	0.77	-	
		@20A, Pulse, T _J = 25 °C	0.87	1.0	
	V _{F2}	@ 5A, Pulse, T _J = 125 °C	0.54	-	V
		@10A, Pulse, T _J = 125 °C	0.62	-	
		@20A, Pulse, T _J = 125 °C	0.73	0.82	
Reverse Current(Per Leg)*	I _{R1}	@V _R = rated V _R , T _J = 25 °C	0.0003	0.25	mA
	I _{R2}	@V _R = rated V _R , T _J = 125 °C	1.6	25	mA
Junction Capacitance(Per Leg)	C _T	@V _R = 5V, T _C = 25 °C, f _{SIG} = 1MHz	835	-	pF
RSM Isolation Voltage(t = 1.0 second, R. H. < =30%, TA = 25 °C)	V _{ISO}	Clip mounting, the epoxy body away from the heatsink edge by more than 0.110" along the lead direction	-	4500	V
		Clip mounting, the epoxy body is inside the heatsink.	-	3500	
		Screw mounting, the epoxy body is inside the heatsink.	-	1500	

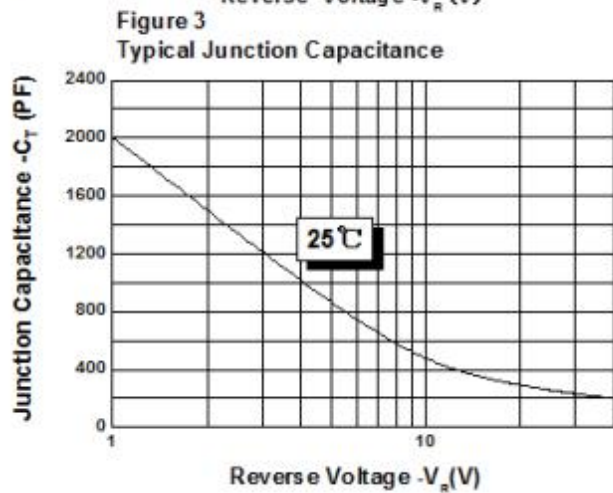
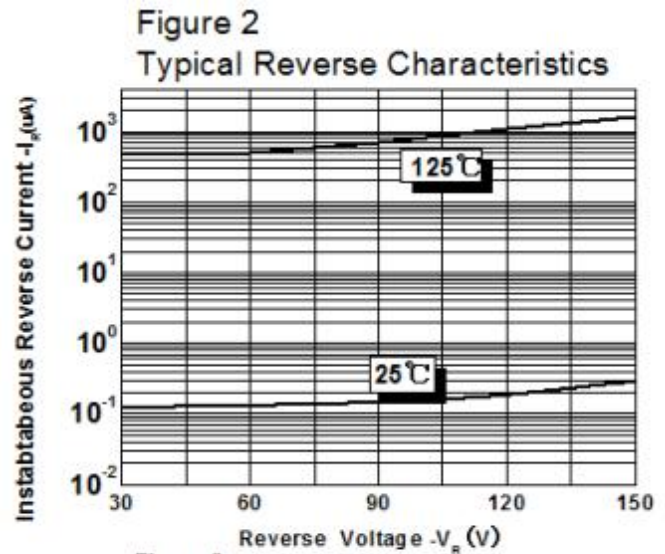
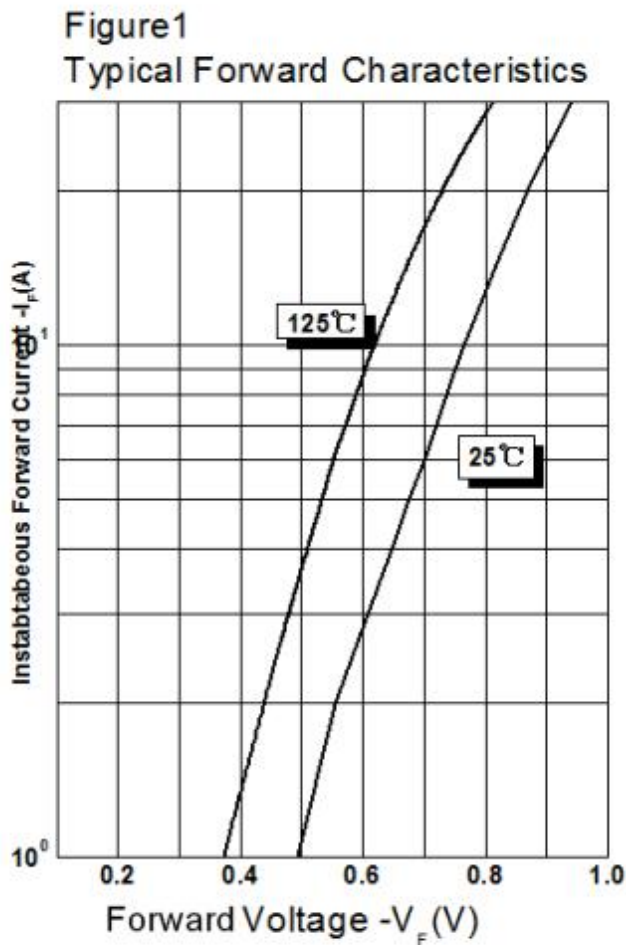
- China - Germany - Korea - Singapore - United States •
- <http://www.smc-diodes.com> - sales@smc-diodes.com •

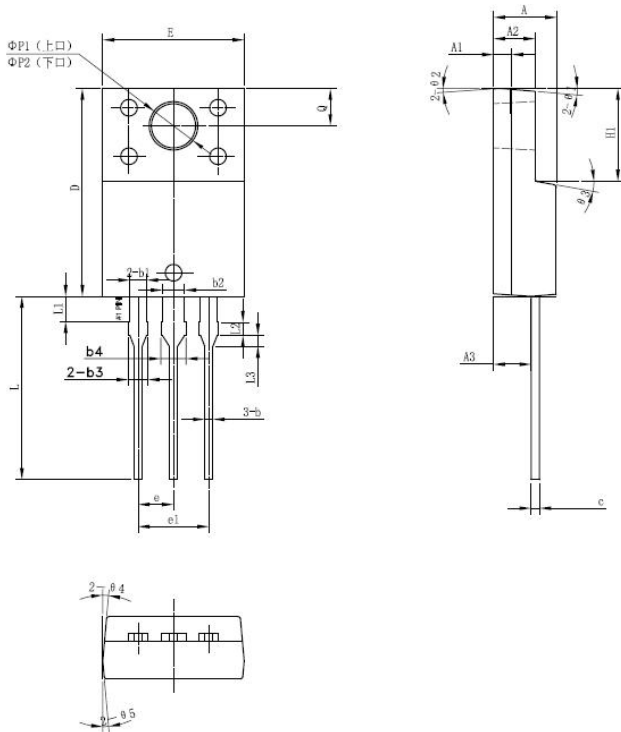
* Pulse width < 300 μ s, duty cycle < 2%

Thermal-Mechanical Specifications:

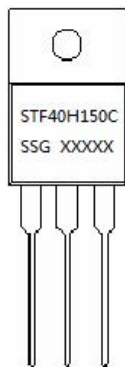
Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T_J	-	-55 to +175	$^{\circ}$ C
Storage Temperature	T_{stg}	-	-55 to +175	$^{\circ}$ C
Typical Thermal Resistance Junction to Case(Per Leg)	$R_{\theta JC}$	DC operation	4.5	$^{\circ}$ C/W
Approximate Weight	wt	-	2	g
Case Style		ITO-220AB		

Ratings and Characteristics Curves



Mechanical Dimensions ITO-220AB


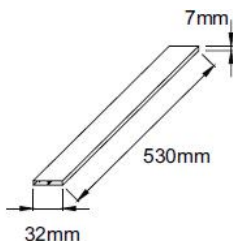
SYMBOL	Millimeters		
	MIN.	TYP.	MAX.
A	4.30	4.50	4.70
A1	1.10	1.30	1.50
A2	2.80	3.00	3.20
A3	2.50	2.70	2.90
b	0.50	0.60	0.75
b1	1.10	1.20	1.35
b2	1.50	1.60	1.75
b3	1.20	1.30	1.45
b4	1.60	1.70	1.85
c	0.50	0.60	0.75
D	14.80	15.00	15.20
E	9.96	10.16	10.36
e		2.55	
e1		5.10	
H1	6.50	6.70	6.90
L	12.70	13.20	13.70
L1	1.60	1.80	2.00
L2	0.80	1.00	1.20
L3	0.60	0.80	1.00
ΦP1(上□)	3.30	3.50	3.70
ΦP2(下□)	2.99	3.19	3.39
Q	2.50	2.70	2.90
Θ1		5°	
Θ2		4°	
Θ3		10°	
Θ4		5°	
Θ5		5°	

Marking Diagram


Where XXXXX is YYWWL

- ST = Device Type
- F = Package type
- 40 = Forward Current (40A)
- H = Tj 175°C
- 150 = Reverse Voltage (150V)
- C = Configuration
- SSG = SSG
- YY = Year
- WW = Week
- L = Lot Number

Cautions: Molding resin
 Epoxy resin III-94V-0

Tube Specification

Ordering Information

Device	Package	Shipping
STF40H150C	ITO-220AB (Pb-Free)	50 pcs/ tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

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